

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

1 (currently amended): A nonvolatile semiconductor memory package comprising:

a memory device having a memory cell array including a plurality of nonvolatile semiconductor memory cells;

a control portion configured to control the memory device;

a network interface connectable to a network;

a file management portion connected to the network interface and configured to manage a relationship between a data file ~~given~~ from the network and an address of the memory cell array; and

a memory interface connected to the file management portion and configured to convert a signal ~~given~~ from the network to a signal which is capable of being used at the control portion, wherein the package is wrapped by an insulating material.

2 (original): The nonvolatile semiconductor memory package according to claim 1, wherein the network interface corresponds to a transmission control protocol/internet protocol.

3 (original): The nonvolatile semiconductor memory package according to claim 2, wherein the network interface is connectable to the network by using a file transfer protocol.

4 (original): The nonvolatile semiconductor memory package according to claim 2, wherein the network interface is connectable to the network by using an anonymous file transfer protocol.

5 (original): The nonvolatile semiconductor memory package according to claim 2, wherein the network interface is connectable to the network by using a point-to-point protocol.

6 (original): The nonvolatile semiconductor memory package according to claim 1, wherein the package is also connectable to equipment disconnected from the network.

7 (currently amended): The nonvolatile semiconductor memory package according to claim 6, wherein the package ~~works~~functions as a storage device for the equipment.

8 (new): A detachable memory device comprising:

- a memory device having a memory cell array including a plurality of nonvolatile semiconductor memory cells;

- a control portion configured to control the memory device;

- a network interface connectable to a network;

- a file management portion connected to the network interface and configured to manage a relationship between a data file from the network and an address of the memory cell array; and

- a memory interface connected to the file management portion and configured to convert a signal from the network to a signal which is capable of being used at the control portion.

9 (new): The detachable memory device according to claim 8, wherein the network interface corresponds to a transmission control protocol/internet protocol.

10 (new): The detachable memory device according to claim 8, wherein the network interface is connectable to the network by using a file transfer protocol.

11 (new): The detachable memory device according to claim 8, wherein the network interface is connectable to the network by using an anonymous file transfer protocol.

12 (new): The detachable memory device according to claim 8, wherein the network interface is connectable to the network by using a point-to-point protocol.

13 (new): The detachable memory device according to claim 8, wherein the package is also connectable to equipment disconnected from the network.

14 (new): The detachable memory device according to claim 13, wherein the package functions as a storage device for the equipment.